

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Warren M. Farnworth

Serial No.: 10/043,468

Filed: January 10, 2002

For: METHOD OF FORMING

OVERMOLDED CHIP SCALE PACKAGE

AND RESULTING PRODUCT

Examiner: Unknown

Group Art Unit: 2823

Attorney Docket No.: 3085.4US (96-1033.4)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

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Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)

Doreen Neumann
Typed/printed name of person whose signature is contained above

PRELIMINARY AMENDMENT

Box Non-Fee Amendment Commissioner for Patents Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.